

EECS4201 Computer Architecture

- Instructor
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 - Office LAS2026 Phone ext: 40607
- Research interests
 - Computer Architecture
 - Low power architecture
 - Embedded systems
 - FPGA (in embedded applications)

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EECS4201 Computer Architecture

- Text
 - Computer Architecture: A Quantitative Approach Patterson & Hennessey 5th Ed.
- Class Meeting
 - Tuesdays, Thursdays 10:11:30 CB120
- Office Hours
 - Tuesdays, Thursdays 1:00-3:00pm or by appointment

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EECS4201 Topics

- Introduction
- Instruction level parallelism
- Data level parallelism (SIMD and GPU)
- Thread level parallelism
- Memory hierarchy design
- Introduction to warehouse-scale computers
- SOC and MPSOC

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Grading EECS4201

Grades are distributed as follows

HW/Assignments
 Quizzes
 Midterm
 Paper review – groups of 2
 Final
 10%
 40%

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Grading EECS5501

Grades are distributed as follows

HW/Assignments
 Quizzes
 Midterm
 Project
 Final
 10%
 20%
 35%

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Assumptions

- I assume that you already completed EECS2021 or equivalent (you know about these topics).
 - Assembly language
 - RISC architecture
 - ALU architecture
 - Pipelining and hazards
 - Memory hierarchy and cache organization !?

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Computer Architecture

- Why study computer architecture
- Hardware/Architecture
 - Design better, faster, cheaper computers that use as little energy as possible
- Software
 - Understand the architecture to squeeze as much performance for your code as possible

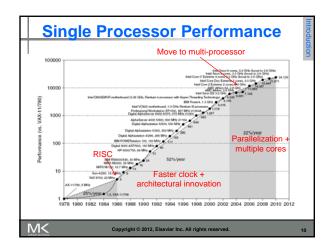
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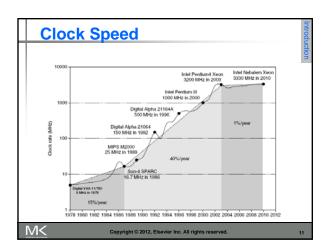
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Computer Technology

- Performance improvements:
 - Improvements in semiconductor technology
 - Feature size, clock speed
 - Improvements in computer architectures
 - Enabled by HLL compilers, UNIX
 - Lead to RISC architectures
 - Together have enabled:
 - Lightweight computers
 - Productivity-based managed/interpreted programming languages

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Current Trends in Architecture ■ Cannot continue to leverage Instruction-Level parallelism (ILP) ■ Single processor performance improvement ended in 2003 ■ New models for performance: ■ Data-level parallelism (DLP) ■ Thread-level parallelism (TLP) ■ Request-level parallelism (RLP) ■ These require explicit restructuring of the application

Classes of Computers

- Personal Mobile Device (PMD)
 - e.g. smart phones, tablet computers
 - Emphasis on energy efficiency and real-time
- Desktop Computing
 - Emphasis on price-performance
- Servers
 - Emphasis on availability, scalability, throughput
- Clusters / Warehouse Scale Computers
 - Used for "Software as a Service (SaaS)"
 - Emphasis on availability and price-performance
 - Sub-class: Supercomputers, emphasis: floating-point performance and fast internal networks
- Embedded Computers
- Emphasis: price

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Parallelism

- Classes of parallelism in applications:
 - Data-Level Parallelism (DLP)
 - Task-Level Parallelism (TLP)
- Classes of architectural parallelism:
 - Instruction-Level Parallelism (ILP)
 - Vector architectures/Graphic Processor Units (GPUs)
 - Thread-Level Parallelism Highly coupled
 - Request-Level Parallelism Decoupled

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Flynn's Taxonomy

- Single instruction stream, single data stream (SISD)
- Single instruction stream, multiple data streams (SIMD)
 - Vector architectures
 - Multimedia extensions
 - Graphics processor units
- Multiple instruction streams, single data stream (MISD)
 - No commercial implementation
- Multiple instruction streams, multiple data streams (MIMD)
 - Tightly-coupled MIMD
 - Loosely-coupled MIMD

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Defining Computer Architecture

- "Old" view of computer architecture:
 - Instruction Set Architecture (ISA) design
 - i.e. decisions regarding:
 - registers, memory addressing, addressing modes, instruction operands, available operations, control flow instructions, instruction encoding
- "Real" computer architecture:
 - Specific requirements of the target machine
 - Design to maximize performance within constraints: cost, power, and availability
 - Includes ISA, microarchitecture, hardware

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Trends in Technology

Integrated circuit technology

Transistor density:

Die size:

10-20%/year

Integration overall: 40-55%/year

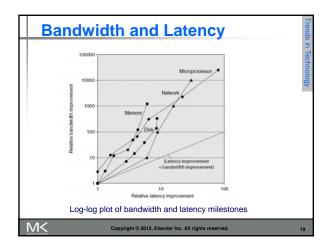
- DRAM capacity: 25-40%/year (slowing)
- Flash capacity: 50-60%/year
 - 15-20X cheaper/bit than DRAM
- Magnetic disk technology: 40%/year
 - 15-25X cheaper/bit then Flash
 - 300-500X cheaper/bit than DRAM

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Bandwidth and Latency

- Bandwidth or throughput
 - Total work done in a given time
 - 10,000-25,000X improvement for processors
 - 300-1200X improvement for memory and disks
- Latency or response time
 - Time between start and completion of an event
 - 30-80X improvement for processors
 - 6-8X improvement for memory and disks



Transistors and Wires

- Feature size
 - Minimum size of transistor or wire in x or y dimension
 - 10 microns in 1971 to .032 microns in 2011 (intel 14nm)
 - Transistor performance scales linearly
 - Wire delay does not improve with feature size!
 - Integration density scales quadratically

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Power and Energy

- Problem: Get power in, get power out
- Power vs. Energy: Which is more important?
- Thermal Design Power (TDP)
 - Characterizes sustained power consumption
 - Used as target for power supply and cooling system
 - Lower than peak power, higher than average power consumption
- Clock rate can be reduced dynamically to limit power consumption
- Energy per task is often a better measurement

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Dynamic Energy and Power

- Dynamic energy
 - Transistor switch from $0 \rightarrow 1$ or $1 \rightarrow 0$
 - ½ x Capacitive load x Voltage²
- Dynamic power
 - ½ x Capacitive load x Voltage² x Frequency switched
- Reducing clock rate reduces power, not energy

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Power

- Intel 80386 consumed ~ 2 W
- 3.3 GHz Intel Core i7 consumes 130 W
- Heat must be dissipated from 1.5 x 1.5 cm chip
- This is the limit of what can be cooled by air
- Hot spot ?

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Reducing Power

- Techniques for reducing power:
 - Do nothing well
 - Dynamic Voltage-Frequency Scaling
 - Design for typical case: for example PMD are idle most of the time, low power state for DRAM, disks
 - Overclocking, turning off cores

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Static Power

- Static power consumption
 - Current_{static} x Voltage
 - Leakage current (power could be as high as 50% of total power consumption) increases with decreasing the transistor size (λ)
 - Scales with number of transistors
 - To reduce: power gating

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Trends in Cost

- Cost driven down by learning curve
 - Yield
- DRAM: price closely tracks cost
- Microprocessors: price depends on volume
 - 10% less for each doubling of volume

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Integrated Circuit Cost

Integrated circuit

 $Cost of integrated circuit \equiv \frac{Cost of die + Cost of testing die + Cost of packaging and final test}{Final test yield}$

Cost of die = Cost of wafer

Dies per wafer × Die yield

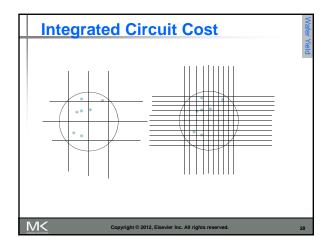
Dies per wafer = $\frac{\pi \times (\text{Wafer diameter/2})^2}{\text{Die area}} - \frac{\pi \times \text{Wafer diameter}}{\sqrt{2 \times \text{Die area}}}$

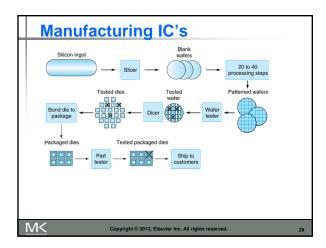
Bose-Einstein formula:

Die yield = Wafer yield $\times 1/(1 + Defects per unit area \times Die area)^N$

- Defects per unit area = 0.016-0.057 defects per square cm (2010)
- N = process-complexity factor = 11.5-15.5 (40 nm, 2010)

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■ Service Level Agreement (SLA) guarantees a certain level of dependability. ■ Module reliability ■ Mean time to failure (MTTF) ■ Mean time between failures (MTBF) = MTTF + MTTR ■ Availability = MTTF / (MTTF+MTTR) ■ Cost of failure: varies hugely depending on applications

■ Example 10 disks 1,000,000-hour MTTF	
1 ATA controller 500,000-hour MTTF 1 Power supply 200,000-hour MTTF	
1 Fan 200,000-hour MTTF ATA cable 1,000,000-hour MTTF Acquired lifetimes are expensationly	
 Assume lifetimes are exponentially distributed and failures are independent 	
■ Calculate MTTF	
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]
■ What if we added one extra power supply	
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Measuring Performance	1
Typical performance metrics:	
Response time Throughput	
Speedup of X relative to Y Execution time _Y / Execution time _X	
Execution time Wall clock time: includes all system overheads CPU time: only computation time	
Benchmarks	
Kernels (e.g. matrix multiply) Toy programs (e.g. sorting) Synthetic benchmarks (e.g. Dhrystone) Benchmark suites (e.g. SPEC06fp, TPC-C)	
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benchmarks

- Embedded Microprocessor Benchmark Consortium
 - www.eembc.org
 - 41 kernels
- SPEC: Standard Performance Evaluation Corporation
 - www.spec.org
 - Covers many application classes (desktop, SPEC Web, SPECFS)
- TPC: Transaction Processing Council
 - www.tpc.org
 - Database transactions

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Reporting Performance

Many programs, how can we capture performance using a single number?

 P1
 P2
 P3

 Machine-A
 10
 8
 25

 Machine-B
 12
 9
 20

 Machine-C
 8
 8
 30

- Sum of execution time
- Sum of weighted execution time
- Geometric mean of execution time

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Reporting Performance

 machine_A
 M/C_B
 M/C_C

 P1
 1sec
 10sec
 20sec

 P2
 1000sec
 100sec
 20sec

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Reporting Performance

- Time = $TC \times CPI \times IC$
- Must be reproducible
- Complete description of the computer and compiler flags.
- Usually, compared to a standard machine execution time SPECRatioA = T_{ref}/T_A.
- Geometric mean

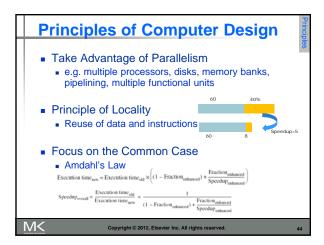
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Name	Description	IC×109	CPI	Tc (ns)	Exec time	Ref time	SPECraf
perl	Interpreted string processing	2,118	0.75	0.40	637	9,777	15
bzip2	Block-sorting compression	2,389	0.85	0.40	817	9,650	11
gcc	GNU C Compiler	1,050	1.72	0.47	24	8,050	11
mcf	Combinatorial optimization	336	10.00	0.40	1,345	9,120	6
go	Go game (AI)	1,658	1.09	0.40	721	10,490	14
hmmer	Search gene sequence	2,783	0.80	0.40	890	9,330	10
sjeng	Chess game (Al)	2,176	0.96	0.48	37	12,100	14
libquantum	Quantum computer simulation	1,623	1.61	0.40	1,047	20,720	19
h264avc	Video compression	3,102	0.80	0.40	993	22,130	22
omnetpp	Discrete event simulation	587	2.94	0.40	690	6,250	9
astar	Games/path finding	1,082	1.79	0.40	773	7,020	9
xalancbmk	XML parsing	1,058	1 2.70	0.40	1,143	6,900	6
Geometric m	Geometric mean					11.7	
	High cache miss rate	es /					
	riigir cacric miss ratt						

Name	Description	IC×109	CPI	Tc (ns)	Exec time	Ref time	SPECratio
perl	Interpreted string processing	2,252	0.60	0.376	508	9,770	19.2
bzip2	Block-sorting compression	2,390	0.70	0.376	629	9,650	15.4
gcc	GNU C Compiler	794	1.20	0.376	358	8,050	22.5
mcf	Combinatorial optimization	221	2.66	0.376	221	9,120	41.2
go	Go game (AI)	1,274	1.10	0.376	527	10,490	19.9
Hmmer	Search gene sequence	2,616	0.60	0.376	590	9,330	15.8
sjeng	Chess game (AI)	1,948	0.80	0.376	586	12,100	20.7
libquantum	Quantum computer simulation	659	0.44	0.376	109	20,720	190.0
h264avc	Video compression	3,793	0.50	0.376	713	22,130	31.0
omnetpp	Discrete event simulation	367	2.10	0.376	290	6,250	21.5
astar	Games/path finding	1,250	1.00	0.376	470	7,020	14.9
xalancbmk	XML parsing	1,045	0.70	0.376	275	6,900	25.1
Geometric m	ean						25.7

SPEC Power Benchmark ■ Power consumption of server at different workload levels ■ Performance: ssj_ops/sec ■ Power: Watts (Joules/sec) Overall ssj_ops per Watt = \(\bigcup_{i=0}^{10} \ssj_ops_i \right) / \(\bigcup_{i=0}^{10} \text{power}_i \)

	ver_ssj2008	
Target Load %	Performance (ssj_ops/sec)	Average Power (Watts
100%	231,867	295
90%	211,282	286
80%	185,803	275
70%	163,427	265
60%	140,160	256
50%	118,324	246
40%	920,35	233
30%	70,500	222
20%	47,126	206
10%	23,066	180
0%	0	141
Overall sum	1,283,590	2,605
∑ssj_ops/ ∑power		493



Principles of Computer Design The Processor Performance Equation CPU time = CPU clock cycles for a program × Clock cycle time CPU time = CPU clock cycles for a program Clock rate CPI = CPU clock cycles for a program Instruction count CPU time = Instruction count × Cycles per instruction × Clock cycle time Instructions × Clock cycles × Seconds Program × Clock cycles × Seconds Program = CPU time

Princi	ples	of	Com	puter	Desi	iar
						. 3-

 Different instruction types having different CPIs

$$CPU clock cycles = \sum_{i=1}^{n} IC_i \times CPI_i$$

CPU time =
$$\left(\sum_{i=1}^{n} IC_i \times CPI_i\right) \times Clock$$
 cycle time

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Example)	Example
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Fallacies and Pitfalls	
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